


MITSUBISHI Nch POWER MOSFET

# FS40SM-5

HIGH-SPEED SWITCHING USE

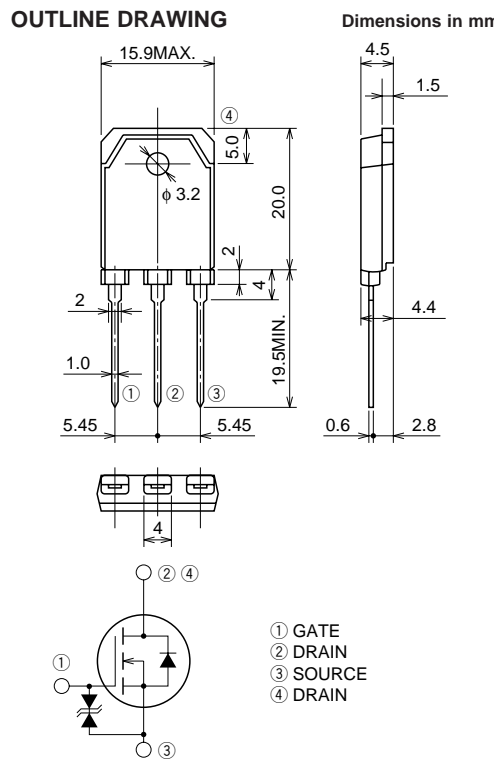
**FS40SM-5**



● V<sub>DSS</sub> ..... 250V  
 ● r<sub>DS (ON)</sub> (MAX) ..... 0.086Ω  
 ● I<sub>D</sub> ..... 40A

**OUTLINE DRAWING**

Dimensions in mm



① GATE  
 ② DRAIN  
 ③ SOURCE  
 ④ DRAIN

**TO-3P**

**APPLICATION**

SMPS, DC-DC Converter, battery charger, power supply of printer, copier, HDD, FDD, TV, VCR, personal computer etc.

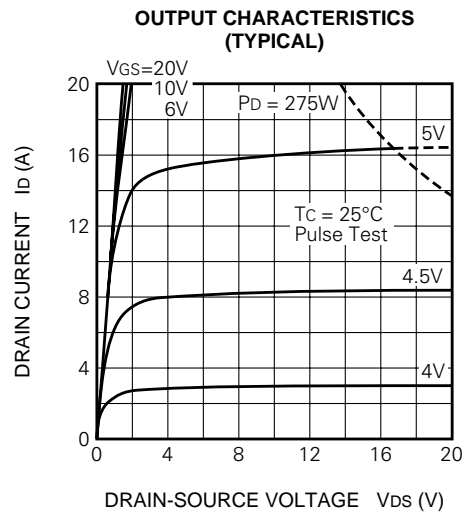
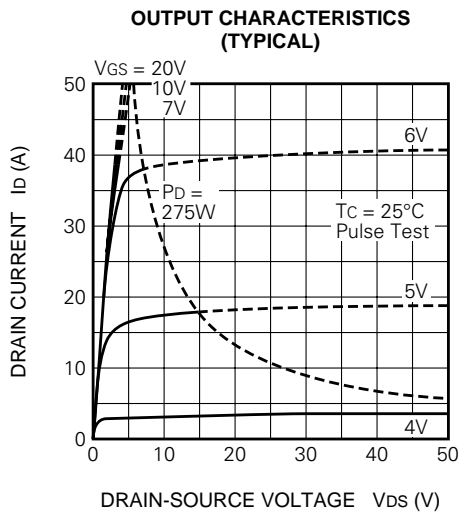
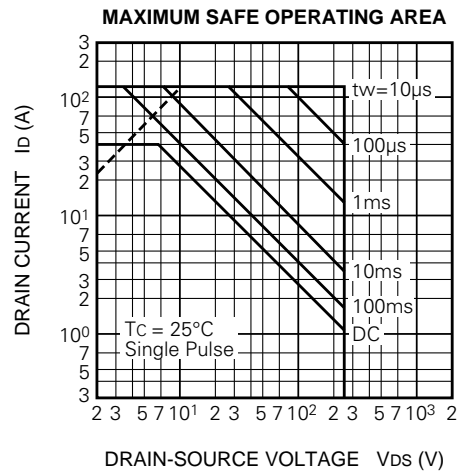
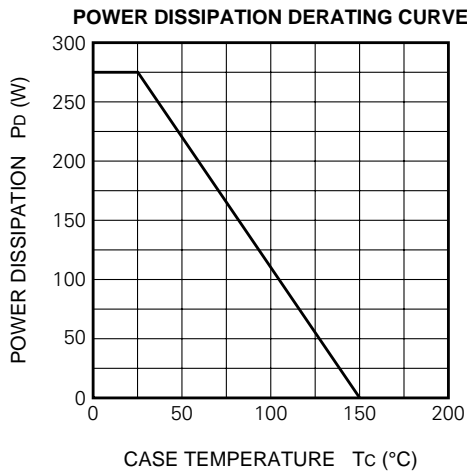
**MAXIMUM RATINGS** (T<sub>c</sub> = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>DSS</sub>	Drain-source voltage	V <sub>GS</sub> = 0V	250	V
V <sub>GSS</sub>	Gate-source voltage	V <sub>DS</sub> = 0V	±30	V
I <sub>D</sub>	Drain current		40	A
I <sub>DM</sub>	Drain current (Pulsed)		120	A
P <sub>D</sub>	Maximum power dissipation		275	W
T <sub>ch</sub>	Channel temperature		-55 ~ +150	°C
T <sub>stg</sub>	Storage temperature		-55 ~ +150	°C
—	Weight	Typical value	4.8	g

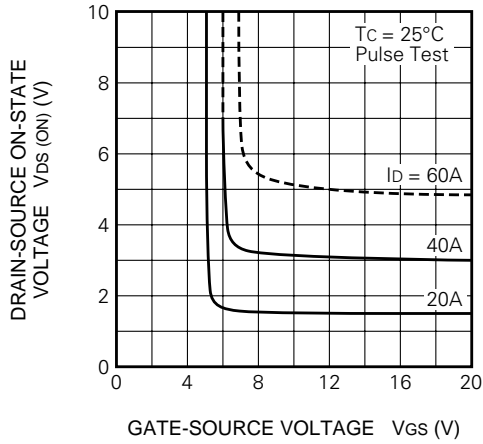
**ELECTRICAL CHARACTERISTICS** ( $T_{ch} = 25^{\circ}\text{C}$ )

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V (BR) DSS	Drain-source breakdown voltage	$I_D = 1\text{mA}, V_{GS} = 0\text{V}$	250	—	—	V
V (BR) GSS	Gate-source breakdown voltage	$I_G = \pm 100\mu\text{A}, V_{DS} = 0\text{V}$	$\pm 30$	—	—	V
I <sub>GSS</sub>	Gate-source leakage current	$V_{GS} = \pm 25\text{V}, V_{DS} = 0\text{V}$	—	—	$\pm 10$	$\mu\text{A}$
I <sub>DSS</sub>	Drain-source leakage current	$V_{DS} = 250\text{V}, V_{GS} = 0\text{V}$	—	—	1	mA
V <sub>GS(th)</sub>	Gate-source threshold voltage	$I_D = 1\text{mA}, V_{DS} = 10\text{V}$	2	3	4	V
r <sub>DS(ON)</sub>	Drain-source on-state resistance	$I_D = 20\text{A}, V_{GS} = 10\text{V}$	—	0.066	0.086	$\Omega$
V <sub>DS(ON)</sub>	Drain-source on-state voltage	$I_D = 20\text{A}, V_{GS} = 10\text{V}$	—	1.32	1.72	V
y <sub>fs</sub>	Forward transfer admittance	$I_D = 20\text{A}, V_{DS} = 10\text{V}$	12.0	18.0	—	S
C <sub>iss</sub>	Input capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	—	2850	—	pF
C <sub>oss</sub>	Output capacitance		—	580	—	pF
C <sub>rss</sub>	Reverse transfer capacitance		—	110	—	pF
t <sub>d(on)</sub>	Turn-on delay time	$V_{DD} = 150\text{V}, I_D = 20\text{A}, V_{GS} = 10\text{V}, R_{GEN} = R_{GS} = 50\Omega$	—	45	—	ns
t <sub>r</sub>	Rise time		—	125	—	ns
t <sub>d(off)</sub>	Turn-off delay time		—	310	—	ns
t <sub>f</sub>	Fall time		—	140	—	ns
V <sub>SD</sub>	Source-drain voltage	$I_S = 20\text{A}, V_{GS} = 0\text{V}$	—	1.5	2.0	V
R <sub>th(ch-c)</sub>	Thermal resistance	Channel to case	—	—	0.45	$^{\circ}\text{C/W}$

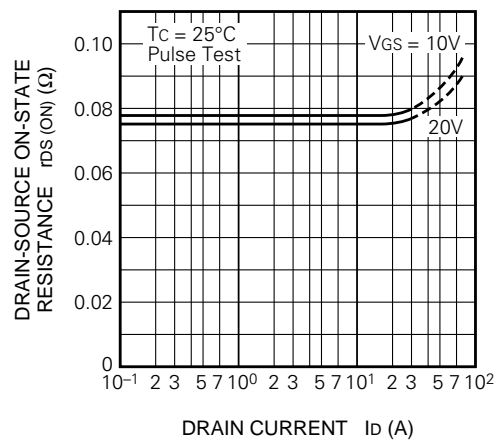
**PERFORMANCE CURVES**



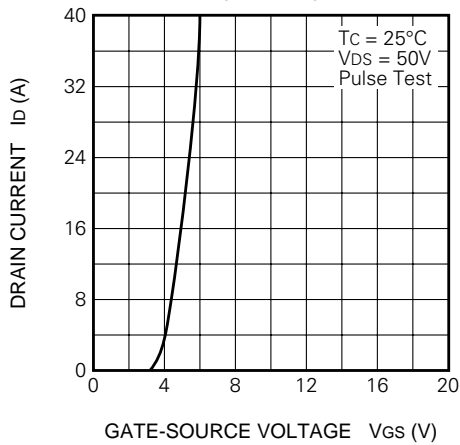
**ON-STATE VOLTAGE VS. GATE-SOURCE VOLTAGE (TYPICAL)**



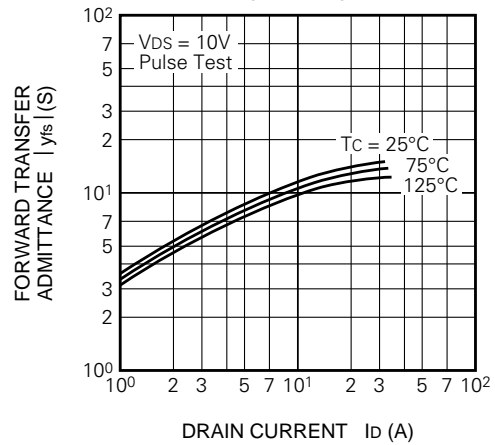
**ON-STATE RESISTANCE VS. DRAIN CURRENT (TYPICAL)**



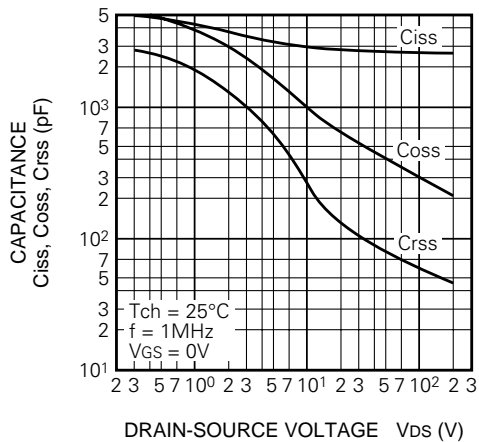
**TRANSFER CHARACTERISTICS (TYPICAL)**



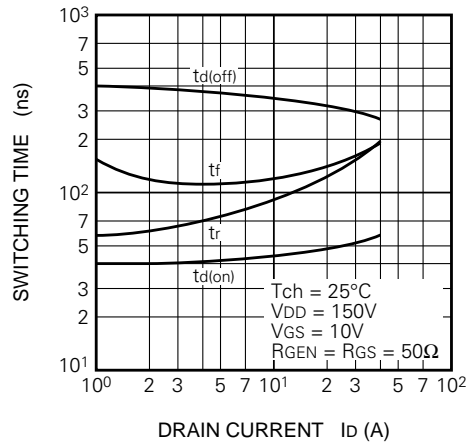
**FORWARD TRANSFER ADMITTANCE VS. DRAIN CURRENT (TYPICAL)**



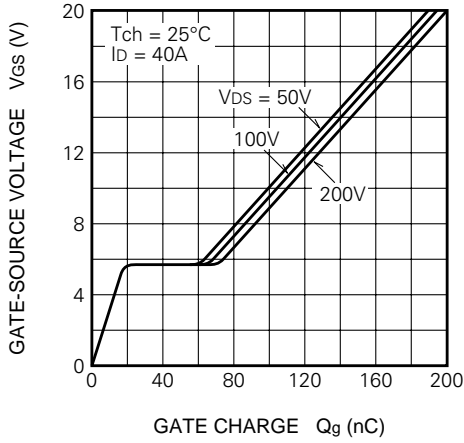
**CAPACITANCE VS. DRAIN-SOURCE VOLTAGE (TYPICAL)**



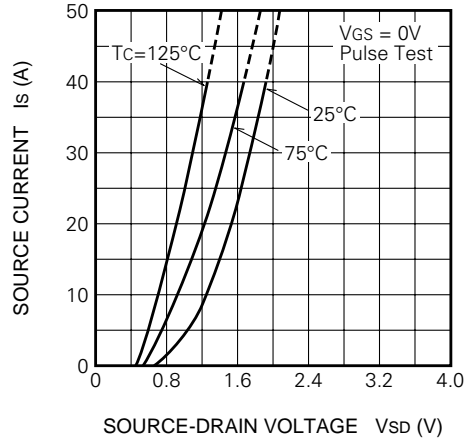
**SWITCHING CHARACTERISTICS (TYPICAL)**



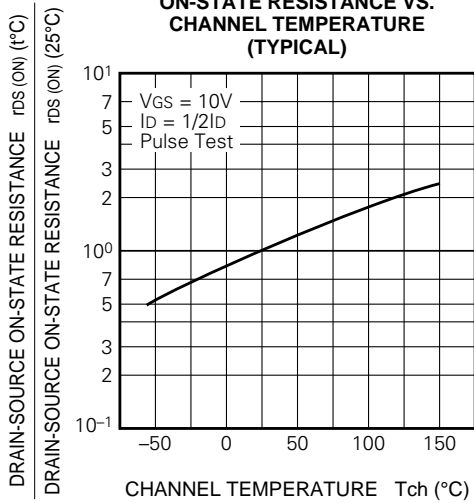
**GATE-SOURCE VOLTAGE VS. GATE CHARGE (TYPICAL)**



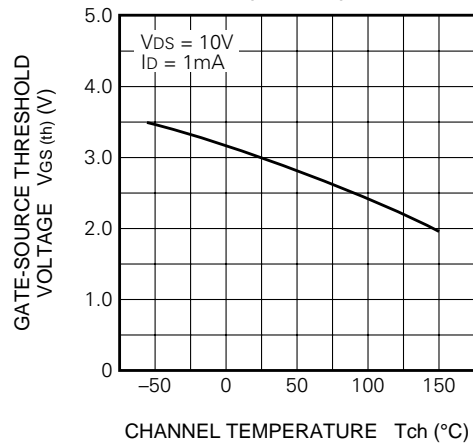
**SOURCE-DRAIN DIODE FORWARD CHARACTERISTICS (TYPICAL)**



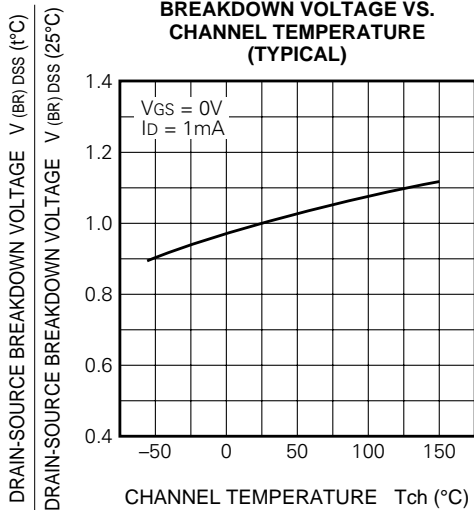
**ON-STATE RESISTANCE VS. CHANNEL TEMPERATURE (TYPICAL)**



**THRESHOLD VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)**



**BREAKDOWN VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)**



**TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS**

